

**5W - 28V - 1GHz**  
**GOLD METALLISED MULTI-PURPOSE**  
**SILICON DMOS RF FET**

**FEATURES**

- METAL GATE
- EXTRA LOW  $C_{rss}$
- BROAD BAND
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN

**APPLICATIONS**

- HF/VHF/UHF COMMUNICATIONS  
from DC to 2 GHz

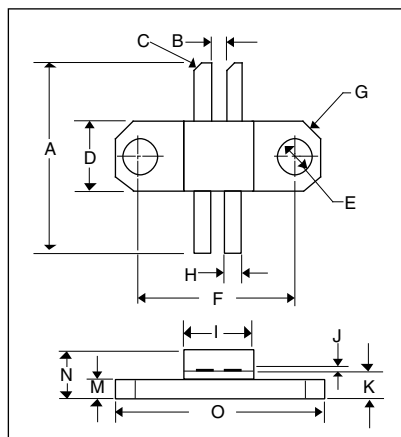
**ABSOLUTE MAXIMUM RATINGS**  
( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)

$P_D$	Power Dissipation	35W
$BV_{DSS}$	Drain-source breakdown voltage	65V
$V_{GSS}$	Gate-source voltage	$\pm 20V$
$I_D$	Drain Current	2A
$T_{stg}$	Storage temperature	65 to 150°C
$T_j$	Maximum operating junction temperature	200°C
$R_{THj-case}$	Thermal resistance junction-case	Max. 5.0°C/W

**ELECTRICAL CHARACTERISTICS** ( $T_{CASE} = 25^{\circ}C$  unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<u>PER SIDE</u>					
$BV_{DSS}$	Breakdown voltage, drain source $V_{GS}=0$ $I_D=10mA$	65			Vdc
$I_{DSS}$	Drain leakage current $V_{DS}=28V$ $V_{GS}=0$			0.2	mAdc
$I_{GSS}$	Gate leakage current $V_{GS}=20V$ $V_{DS}=0$			1	$\mu$ Adc
$V_{GS(th)}$	Gate threshold voltage $I_D=10mA$ $V_{DS}=V_{GS}$	1		7	Vdc
$g_{fs}$	Transconductance (300 $\mu$ s pulse) $V_{DS}=10V$ $I_D=.2A$	0.2			Mhos
<u>TOTAL DEVICE</u>					
$G_{PS}$	Common source power gain $P_o=5W$	13			dB
$\eta$	Drain efficiency $V_{DS}=28V$ $I_{DQ}=.4A$	40			%
VSWR	Load mismatch tolerance $f=1GHz$	20:1			
<u>PER SIDE</u>					
$C_{iss}$	Input capacitance $V_{DS}=0V$ $V_{GS}=-5V$ $f=1MHz$			12	pF
$C_{oss}$	Output capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			6	pF
$C_{rss}$	Reverse transfer capacitance $V_{DS}=28V$ $V_{GS}=0$ $f=1MHz$			0.5	pF

**DIMENSIONS**



DM	Millimeter	TOL	Inches	TOL
A	16.38	.26	.645	.010
B	1.52	.13	.060	.005
C	45°	5°	45°	5°
D	6.35	.13	.250	.005
E	3.30	.13	.130	.005
F	14.22	.13	.560	.005
G	x 45°	.13	.05 x 45°	.005
H	1.52	.13	.060	.005
I	6.35	.13	.250	.005
J	.13	.02	.005	.001
K	2.16	.13	.085	.005
M	1.52	.13	.060	.005
N	5.08	MAX	.200	MAX
O	18.90	5°	.744	.005

**HAZARDOUS MATERIAL WARNING**

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area. THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

U.S. PATENTS 5,121,176 & 5,179,032  
GLOBAL PATENTS PENDING





\*D2003

\*PSPICE MODEL FOR POINT NINE RF N-CHANNEL VERTICAL DMOS POWER FET

\*May 2004

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*          _____GATE
*          I   _____DRAIN
*          I   I   _____SOURCE
*          I   I   I
.SUBCKT D2003  10  20  30
*Cin1,Cin2 & Lin model the input side of the package
Cin1  10   30   0.38p
Lin   10   11   0.71n
Cin2  11   30   0.38p

LG    11   12   1n      ;Gate bond wire inductance
CGS   12   13   10.6p   ;Gate-source capacitance
MOS   14   12   13   13  D2003 L=0.9U W=0.0109   ;D G S B LEVEL1
JFET  16   13   14      D2003                   ;D G S
DBODY 13   16      D2003                   ;P N
LS    13   30   0.5n    ;Source bond wire inductance
CGD   12   16   0.3p    ;Gate-drain feedback capacitance

*Cout1,Cout2 & Lout model the output side of the package
Cin1  10   30   0.38p
Lin   10   11   0.71n
Cin2  11   30   0.38p

.MODEL D2003  NMOS (VTO=3.52 KP=7.77E-4 LAMBDA=0.0224 RD=0.6 RS=2.7)
.MODEL D2003  NJF  (VTO=-5.8 BETA=0.0366 LAMBDA=1.357)
.MODEL D2003  D    (CJO=15P RS=0.25 VJ=0.7 M=0.33 BV=70)

.ENDS
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